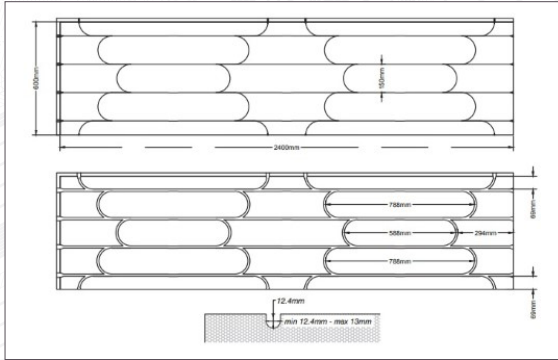


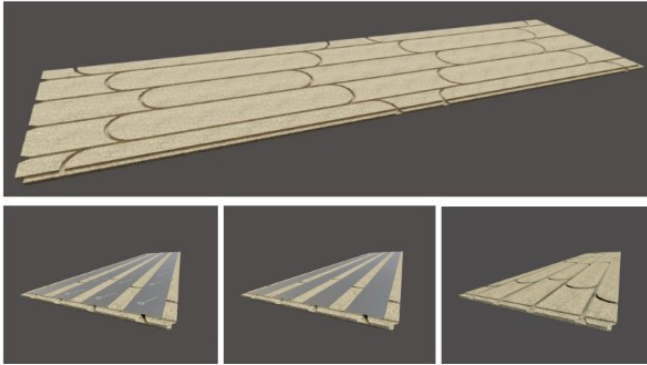
CHIPBOARD PANEL

GENERAL PANEL ARRANGEMENT



Therm

Options & Enhancements



Technical Data - Standard Panel

Product	PS Tongue & Groove Chipboard to BSEN312
Floor Construction:	Joisted or Battened
Dimensions:	2400 x 600 mm
Thickness:	22 mm
Panel Weight (With water & inc. 6 mm ply):	18.9 mm
Pipe Centres:	150
Pipe Channels/External Pipe Diameter:	12 mm
100mm Wide Foil Diffuser Strips:	50 um (micron)
Joist Centres:	< 600 mm
Thermal Conductivity:	0.14 W/mK
Low Emission Grade E1 (Formaldehyde EN120):	< 8.0 mg per 100g

KH Values available on request for calculating outputs to BSEN1264

EXPLORE THE *Warmth*